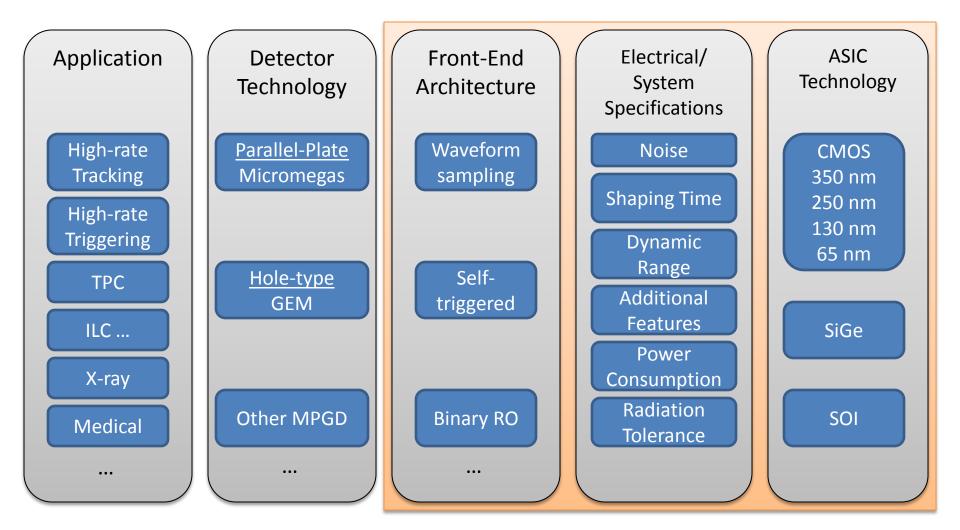
From Chip Matrix to the 'Ideal Chip' for MPGD

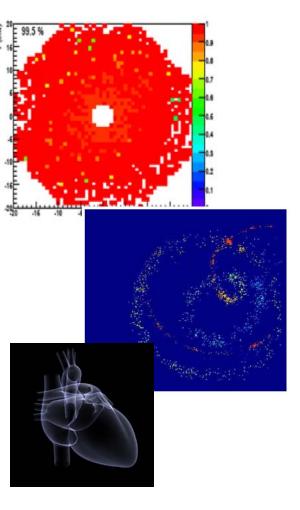
Sorin Martoiu, CERN PH/DT

"Ideal Chip" Specification

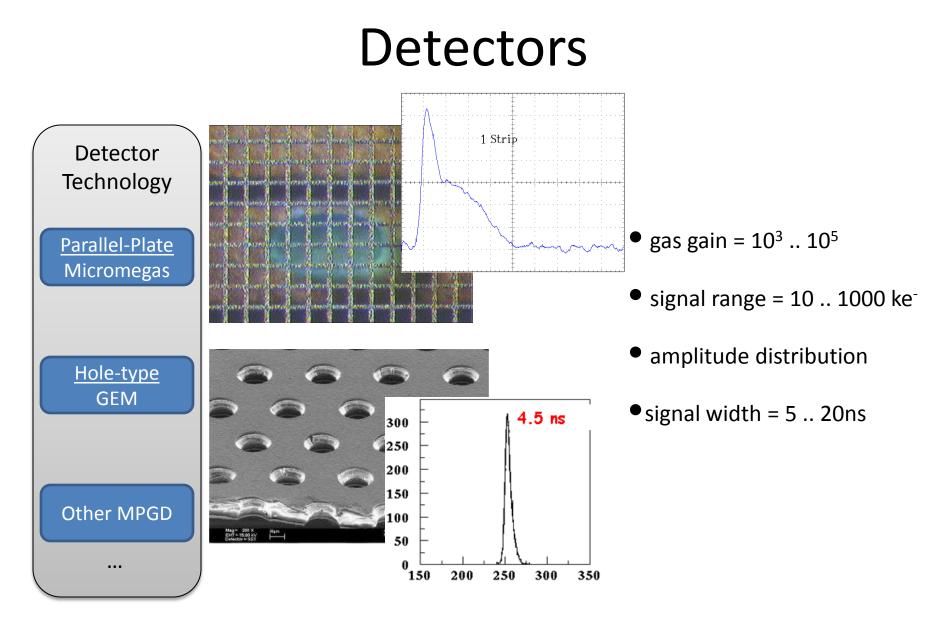


Applications



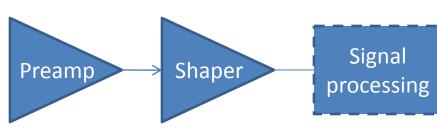


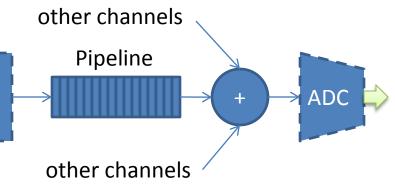
- total rate = ... 25 kHz/mm²
- rate/channel = ?
- spatial resolution = 10 ... 100 um
- temporal resolution = 1 .. 25 ns
- energy resolution = ?
- efficiency = 95 ... 99 %



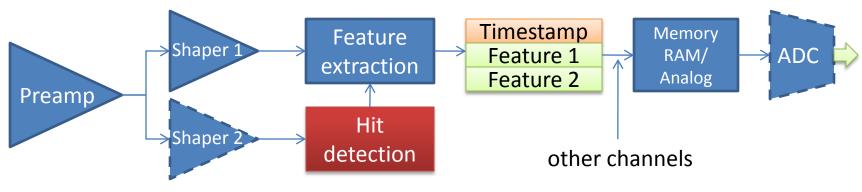
Front-End Architecture

• Waveform sampling





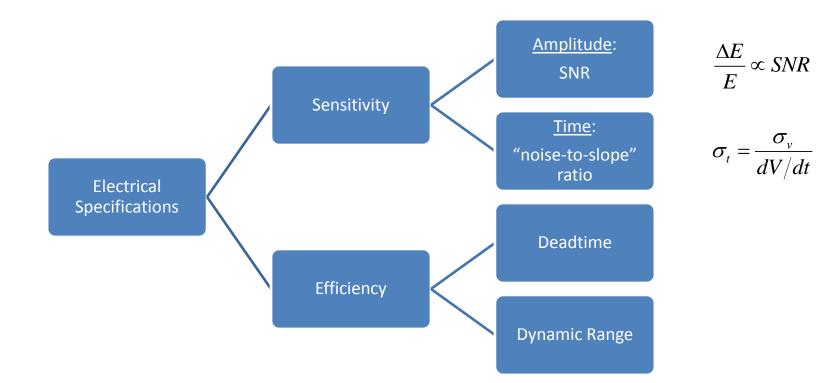
Self-triggered channel



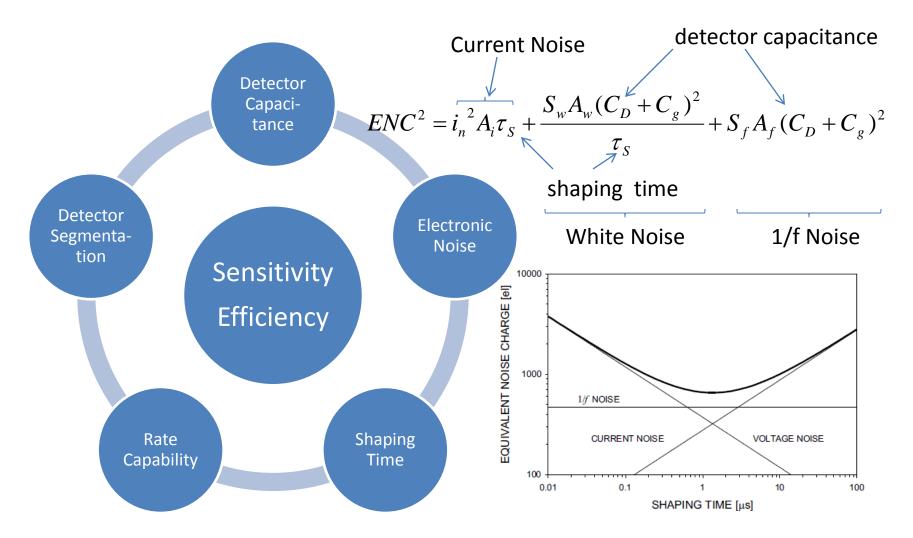
Front-End Architecture

	Pros	Cons
Waveform sampling •analog: <i>APV25, Beetle</i> •binary: <i>VFAT</i> •digital: <i>(S)ALTRO, SVX4</i>	 simple (relatively) versatile off-line data processing pile-up rejection/detection systematic error correction advanced feature extraction data rate ~ trigger rate 	 high data/event readout time needs external trigger no zero-suppression
Self-triggered channel Example: MSGCROC	 zero-suppression optimal data/event 	 less versatile pile-up rejection difficult limited off-line processing data rate ~ event rate high R/O bandwidth

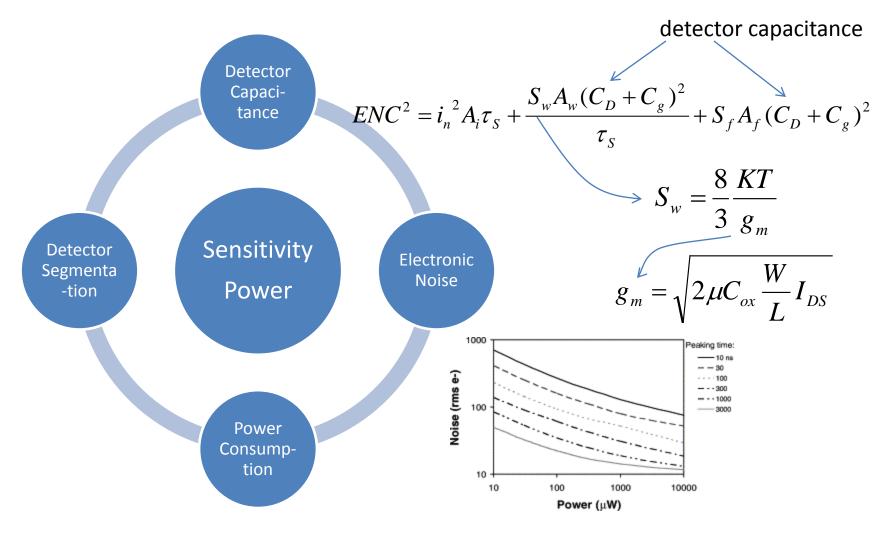
Electrical Specifications



Sensitivity vs. Efficiency



Sensitivity vs. Power



Capacitive Matching

• 1/f noise dominant

• white noise dominant

• No preamplifier can provide optimum noise performance for every detector

10

Technology

CMOS scaling

- better noise performance
- lower dynamic range
- optimum technology for analog design appears to be around the 0.25um node
- Digital circuits clearly benefit from scaling
- <u>Smaller ADCs</u>
- More powerful digital signal processing
- (Auto)calibration and error correction digital circuits could compensate the analog performance deficit

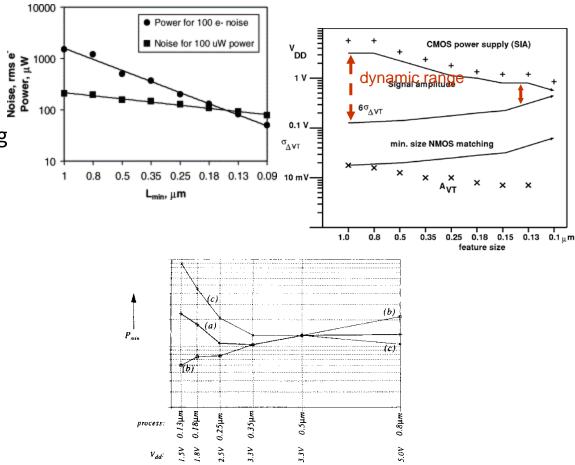


Fig. 8. Minimum power consumption for a voltage follower circuit (with constant topology, SINAD and maximum signal frequency). (a) Made in various processes, operated at their corresponding supply voltages. (b) Made in various processes, all operated at $V_{dd} = 3.3$ V. (c) All made in 0.5- μ m CMOS, operated at various supply voltages.

Features

Chip matrix

Name	Exp	Det	#ch	Shaper (ns)	Noise	Range (fC)	Pol.	ADC	f (MHz)	P/ch. (mW)	Feat.	Tech	Rad hard
APV25	CMS	Si strip	128	50	270+38e/pF	20	both	A	40	2.7	PD, PR	0.25 CMOS	10
AFTER	T2K	TPC	72	100-2000 s-gauss	(350-1800) + (22-1.8)e/pF	19	both	А	1-50 (100)	7.5	VG,VS	0.35 CMOS	no
MSGCROC	DETNI	Gas strip	32	T: 25 E: 85	2000e @ 40pF	800	both	A,1	2ns TDC		VG, ZS	0.35 CMOS	no
Beetle	LHCb		128	25	500+50e/pF	17.5	both	A/1	40	5.2	F-OR	0.25 CMOS	40
VFAT	тотем		128	22	650+50e/pF	18.5 (cal)	both	1	40	4.47	F-OR	0.25 CMOS	50
NINO	ALICE	TPC	8	1	1900+165/pF	2000	both	1	async	30	BR	0.25 CMOS	no
CARIOCA	LHCb	MWPC	8	<15 @ 220pF	2000+40e/pF	250	both	1	async	46	BR	0.25 CMOS	20
PASA+ ALTRO	ALICE TPC	TPC	16	190 _{fwhm} s-gauss	570e @20 pF	160	both	10	20	< 40	BC, TC, ZS	0.35,0.25 CMOS	
SVX4	CDF, D0	Si strip	128	100-360	410+45e/pF	60fC	neg	8	106 (212)	2	ZS	0.25 CMOS	20
SPIROC	ILC, T2K	SiPM	36	A:25-175 T: 10	A: 1/11pe; T:1/24pe	2000 pe	neg	8-12	100ps TDC	0.025 pulse		0.35 <u>SiGe</u>	no
Legend:	PD = peak detection, PR = pile-up rejection, VG = variable gain, VS = variable shaping, F-OR = fast-OR, BR = baseline restorer, BC = baseline correction, TC = tail correction, DC = data compression, ZS = zero suppression											R =	

- ✓ fast-OR,
- ✓ variable gain,
- ✓ variable shaping,
- ✓ peak detection
- ✓ pile-up rejection,
- ✓ baseline restorer,
- ✓ baseline correction,
- ✓ tail correction,
- ✓ data compression,
- ✓ zero suppression

From Chip Matrix to the Ideal Chip

Name	Ехр	Det	#ch	Shaper (ns)	Noise	Range (fC)	Pol.	ADC	f (MHz)	P/ch. (mW)	Feat.	Tech	Rad hard
APV25	CMS	Si strip	128	50	270+38e/pF	20	both	A	40	2.7	PD, PR	0.25 CMOS	10
AFTER	T2K	TPC	72		(350-1800) + (22-1.8)e/pF	19	both	A	1-50 (100)	7.5	VG,VS	0.35 CMOS	no
MSGCROC	DETNI	Gas strip	32	T: 25 E: 85	2000e @ 40pF	800	both	A,1	2ns TDC		VG, ZS	0.35 CMOS	no
Beetle	<u> LНСЬ</u>		128	25	500+50e/pF	17.5	both	A/1	40	5.2	F-OR	0.25 CMOS	40
VFAT	тотем		128	22	650+50e/pF	18.5 (cal)	both	1	40	4.47	F-OR	0.25 CMOS	50
NINO	ALICE	TPC	8	1	1900+165/pF	2000 th<100	both	1	async	30	BR	0.25 CMOS	no
CARIOCA	LHCb	MWPC	8	<15 @ 220pF	2000+40e/pF	250	both	1	async	46	BR	0.25 CMOS	20
PASA+ ALTRO	ALICE TPC	TPC	16	190 _{fwhm} s-gauss	570e @20 pF	160	both	10	20	< 40	BC, TC, ZS	0.35,0.25 CMOS	
SVX4	CDF, D0	Si strip	128	100-360	410+45e/pF	60fC	neg	8	106 (212)	2	ZS	0.25 CMOS	20
SPIROC	ILC, T2K	SiPM	36	A:25-175 T: 10	A: 1/11pe; T:1/24pe	2000 pe	neg	8-12	100ps TDC	0.025 pulse	dual- gain	0.35 <u>SiGe</u>	no
Legend:	PD = peak detection, PR = pile-up rejection, VG = variable gain, VS = variable shaping, F-OR = fast-OR, BR = baseline restorer, BC = baseline correction, TC = tail correction, DC = data compression, ZS = zero suppression												

- shaping time: 5ns .. 1us
- dynamic range: <100fC
- power: < 10 mW/ch (?)
- ADC accuracy: 10 bits (?)
- TDC accuracy: 1ns

•••

We need an **APV25** chip with <u>variable gain and shaping time</u> like the **AFTER** chip, <u>dynamic range</u> like **MSGCROC**, integrated <u>fast-OR</u> like **Beetle**, <u>integrated ADC</u> like **SVX4**, <u>digital signal processor</u> like **ALTRO**